## ARIES ELECTRONICS, INC. PRODUCTION DEPARTMENT

PROCEDURE NUMBER: A-548	REV. B	PAGE 1 OF 1
PROCEDURE NAME: CLEANING PROCE	EDURE FOR RF MICROSTRI	P SOCKETS
OPERATOR: OPERATOR / TECHNIC	IAN	
***************************************	******	************
AUTHOR: BRUCE DECHILLO		
APPROVED BY: MJS		
RELEASE DATE: June 8, 2006		
***************************************	******	******

- 1.0 <u>SCOPE</u>
- 1.1 THE PURPOSE OF THIS DOCUMENT IS TO DEFINE THE ACCEPTED CLEANING PROCEDURE FOR ARIES' RF MICROSTRIP SOCKETS.
- 2.0 REFERENCE DOCUMENTS
- 2.1 ARIES' DATA SHEET 24001
- 2.2 RDZ-1699 DE-OX II DATA SHEET
- 2.3 RDZ-1699 DE-OX II MATERIAL SAFETY DATA SHEET RD CHEMICAL, 1350 PEAR AVENUE, MOUNTAIN VIEW, CA 94043 PH: 650/962-8004, EMAIL: <u>rdchem@rdchem.com</u>, WEB: <u>www.rdchem.com</u>
- 3.0 MATERIAL REQUIRED
- 3.1 MICROSTRIP SOCKET
- 3.2 ISOPROPYL ALCOHOL
- 3.3 RDZ-1699 DE-OX II
- 4.0 EQUIPMENT REQUIRED (OR EQUIVALENT)
- 4.1 B&L STEREOZOOM 4 MICROSCOPE (IF NEEDED)
- 4.2 TWEEZER
- 4.3 SMALL STAINLESS STEEL CONTAINER OR GLASS BEAKER
- 4.4 HOT PLATE
- 4.5 FIRM-HAIRED SCRATCH BRUSH
- 4.6 EXACTO KNIFE
- 5.0 PROCEDURE
- 5.1 CAUTION: BE CERTAIN TO HANDLE RDZ-1699 DE-OX II ACCORDING TO MANUFACTURERS MSDS.
- 5.2 NOTE: DO NOT PUSH ON THE MICROSTRIP CONTACTS, OR LATCH THE LID, WHILE THE SOCKET IS REMOVED FROM SHIPPING PLATE OR PCB.
- 5.3 WHILE SOCKET IS STILL MOUNTED TO PCB, USE SCRATCH BRUSH AND/OR EXACTO KNIFE TO REMOVE COMPACTED DEBRIS FROM MICROSTRIP CONTACTS. (ALWAYS SCRUB OR SCRAPE CONTACTS IN PARARELL DIRECTION WITH CONTACTS.)
- 5.4 REMOVE SOCKET FROM PCB AND BLOW OFF ANY LOOSE DEBRIS WITH FILTERED AIR.
- 5.5 POUR RDZ-1699 DE-OX II INTO CONTAINER. MAKE SURE THERE IS ENOUGH TO COVER THE CONTACTS WHEN SOCKET IS IMMERSED.
- 5.6 HEAT THE RDZ-1699 DE-OX II ON THE HOT PLATE TO +120°F. (NOT CELSIUS!)
- 5.7 PLACE SOCKET, OR CONTACT BLOCK, INTO CONTAINER AND SOAK FOR 5-6 MINUTES. (NOTE: DO NOT USE ULTRASONIC CLEANER.)
- 5.8 REMOVE SOCKET AND RINSE WITH DISTILLED WATER.
- 5.9 BLOW DRY SOCKET WITH FILTERED AIR AND BAKE SOCKET FOR 10 MINUTES AT 85°C.
- 5.10 WHILE SOCKET IS DRYING, CLEAN PCB TRACES WITH SCRATCH BRUSH AND ALCOHOL.
- BLOW DRY WITH FILTERED AIR. 5.11 MOUNT SOCKET BACK ONTO THE PCB AND CONTINUE TESTING.
- 5.12 REPEAT ABOVE PROCEDURE UNTIL CONTACTS CAN NO LONGER BE USED FOR TEST.